

Application No.: 10/065,103

Docket No.: JCLA9142

In the Claims:

Please amend the claims according to the following listing of claims and substitute it for all prior versions and listings of claims in the application.

1. (currently amended) An under-bump metallurgical structure between the bonding pad of a die and a solder bump made from a lead-tin alloy or a lead-free alloy, comprising:

a metallic layer over the bonding pad; and

a mini bump ~~buffer~~ ~~metallic~~ structure between the metallic layer and the solder bump for reducing the growth of inter-metallic compound between the metallic layer and the solder bump.

Claims 2-13 (canceled)

14. (currently amended) The under-bump metallurgical structure of claim 1-12, wherein the principle constituent of the mini bump is lead.

15. (currently amended) The under-bump metallurgical structure of claim 1-12, wherein the principle constituent of the mini bump is lead-tin alloy.

16. (currently amended) The under-bump metallurgical structure of claim 15-12, wherein the percentage of lead and tin in the lead-tin alloy constituting the mini bump is about 95% lead and 5% tin.

Claims 17-20 (canceled)